

Polishing Slurry

Nanopure™

Nanopure™ Series are designed for the stock removal and final polishing processes in the silicon wafer manufacturing. Nanopure series are characterized as the high functional slurries which create higher flatness, lower defectivity and higher productivity.

Nanopure™ Series

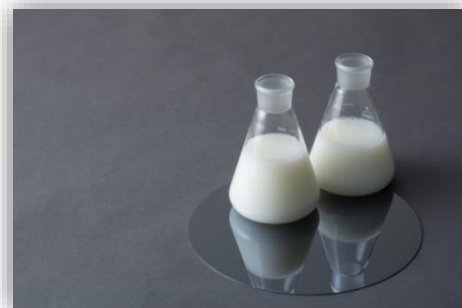
Nanopure™ Series are designed for the stock removal, second polishing, final polishing and edge polishing processes in the silicon wafer manufacturing.

Physical Property

	NP6504	NP6610	NP7310	NP8020H	NP8065	EG1103S1
Particle Type	Colloidal Silica	Colloidal Silica	High Purity Colloidal Silica	High Purity Colloidal Silica	High Purity Colloidal Silica	Colloidal Silica
Silica wt%	28.0	40.0	6.0	9.5	7.8	35.0
pH	11.0-13.0	11.0-12.0	10.3-11.3	10.0-11.0	10.0-11.0	11.1-12.1
Particle Size(nm)	60-120	60-110	60-80	60-80	70-120	80-140
Process	Stock		2nd	Semi-Final	Final	Edge
Advantages	High Removal Rate	Amine Less High Removal Rate	High Dilution	High Removal Rate	High Dilution	Edge Polishing

❑ NITTA DuPont has the complete product line to cover the various request and applications.

❑ Free sample is available for first evaluation.



※ Nanopure™ is the trademark of NITTA DuPont Incorporated.

※ The values such as a physical property indicated, show the standard value. The product specifications are not guaranteed.